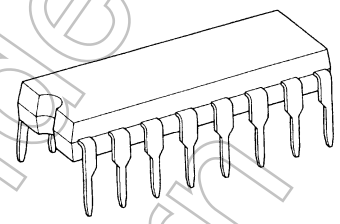
TOSHIBA Bipolar Digital Integrated Circuit Silicon Monolithic

TD62003APG,TD62003AFG,TD62004APG,TD62004AFG

7-channel Darlington Sink Driver

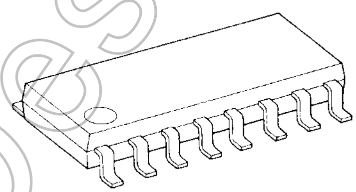
The TD62003APG/AFG and TD62004APG/AFG are high-voltage, high-current darlington drivers comprised of seven NPN darlington pairs.
All units feature integral clamp diodes for switching inductive loads.
Applications include relay, hammer, lamp and display (LED) drivers.

TD62003APG
TD62004APG



DIP16-P-300-2.54A

TD62003AFG
TD62004AFG



SOP16-P-225-1.27

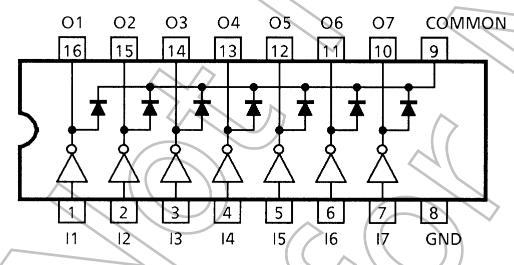
Weight
DIP16−P−300−2.54A : 1.11 g (typ.)
SOP16−P−225−1.27 : 0.16 g (typ.)

Features

- Output current (single output): 500 mA (max)
- High sustaining voltage output: 50 V (min)
- Output clamp diodes
- Inputs compatible with various types of logic
- Package type
  APG: DIP-16 pin
  AFG: SOP-16 pin

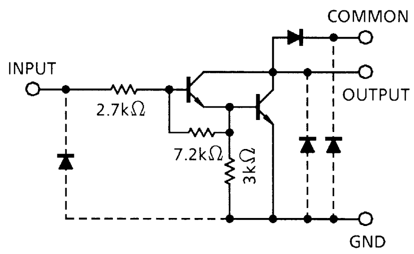
Type	Input base resistor	Designation
TD62003APG/AFG	2.7 kΩ	TTL, 5-V CMOS
TD62004APG/AFG	10.5 kΩ	6-V to 15-V PMOS, CMOS

Pin Connection (top view)

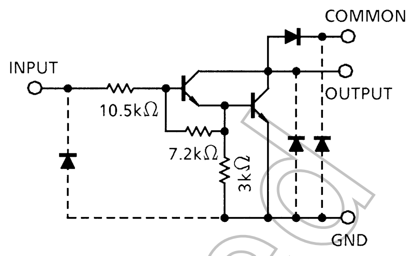


Schematics (each driver)

TD62003APG/AFG



TD62004APG/AFG



Note: The input and output parasitic diodes cannot be used as clamp diodes.

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Output sustaining voltage		$V_{CE\ (SUS)}$	−0.5 to 50	V
Output current		I_{OUT}	500	mA/ch
Input voltage		V_{IN}	−0.5 to 30	V
Clamp diode reverse voltage		V_R	50	V
Clamp diode forward current		I_F	500	mA
Power dissipation	APG	P_D	1.47	W
	AFG		0.625 (Note)	
Operating temperature		T_{opr}	−40 to 85	°C
Storage temperature		T_{stg}	−55 to 150	°C

Note: When mounted on a glass-epoxy PCB (30 mm × 30 mm × 1.6 mm, Cu area: 50%)

Operating Ranges (Ta = –40°C to 85°C)

Characteristics		Symbol	Condition		Min	Typ.	Max	Unit
Output sustaining voltage		$V_{CE\ (SUS)}$	—		0	—	50	V
Output current	APG	I_{OUT}	t_{pw} = 25 ms 7 circuits Ta = 85°C T_j = 120°C	Duty = 10%	0	—	370	mA/ch
				Duty = 50%	0	—	130	
	AFG			Duty = 10%	0	—	233	
				Duty = 50%	0	—	70	
Input voltage		V_{IN}	—		0	—	24	V
Input voltage (output on)	TD62003	$V_{IN\ (ON)}$	I_{OUT} = 400 mA, h_{FE} = 800		2.8	—	24	V
	TD62004				6.2	—	24	
Input voltage (output off)	TD62003	$V_{IN\ (OFF)}$	—		0	—	0.7	
	TD62004				0	—	1.0	
Clamp diode reverse voltage		V_R	—		—	—	50	V
Clamp diode forward current		I_F	—		—	—	350	mA
Power dissipation	APG	P_D	Ta = 85°C		—	—	0.76	W
	AFG		Ta = 85°C (Note)		—	—	0.325	

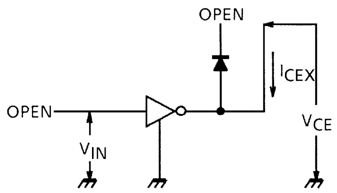
Note: When mounted on a glass-epoxy PCB (30 mm × 30 mm × 1.6 mm, Cu area: 50%)

Electrical Characteristics (Ta = 25°C unless otherwise noted)

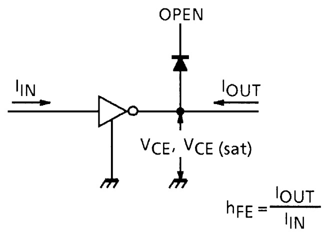
Characteristics		Symbol	Test Circuit	Test Condition		Min	Typ.	Max	Unit
Ooutput leakage current		I_{CEX}	1	V_{CE} = 50 V, Ta = 25°C		—	—	50	μA
				V_{CE} = 50 V, Ta = 85°C		—	—	100	
Collector−emitter saturation voltage		$V_{CE\ (sat)}$	2	I_{OUT} = 350 mA, I_{IN} = 500 μA		—	1.3	1.6	V
				I_{OUT} = 200 mA, I_{IN} = 350 μA		—	1.1	1.3	
				I_{OUT} = 100 mA, I_{IN} = 250 μA		—	0.9	1.1	
DC current transfer ratio		h_{FE}	2	V_{CE} = 2 V, I_{OUT} = 350 mA		1000	—	—	
Input voltage (output on)	TD62003	$I_{IN\ (ON)}$	3	V_{IN} = 2.4 V, I_{OUT} = 350 mA		—	0.4	0.7	mA
	TD62004			V_{IN} = 9.5 V, I_{OUT} = 350 mA		—	0.8	1.2	
Input current (output off)		$I_{IN\ (OFF)}$	4	I_{OUT} = 500 μA, Ta = 85°C		50	65	—	μA
Input voltage (output on)	TD62003	$V_{IN\ (ON)}$	5	V_{CE} = 2 V h_{FE} = 800	I_{OUT} = 350 mA	—	—	2.6	V
					I_{OUT} = 200 mA	—	—	2.0	
	TD62004				I_{OUT} = 350 mA	—	—	4.7	
					I_{OUT} = 200 mA	—	—	4.4	
Clamp diode reverse current		I_R	6	V_R = 50 V, Ta = 25°C		—	—	50	μA
				V_R = 50 V, Ta = 85°C		—	—	100	
Clamp diode forward voltage		V_F	7	I_F = 350 mA		—	—	2.0	V
Input capacitance		C_{IN}	—	—		—	15	—	pF
Turn−ON delay		t_{ON}	8	V_{OUT} = 50 V, R_L = 125 Ω C_L = 15 pF		—	0.1	—	μs
Turn−OFF delay		t_{OFF}				—	0.2	—	

Test Circuit

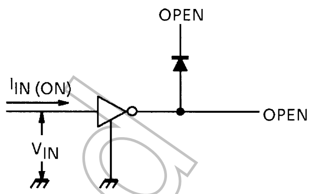
1. I_{CEX}



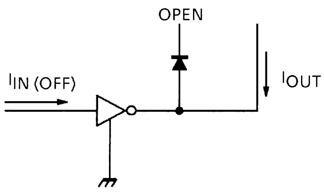
2. $V_{CE\ (sat)}$, h_{FE}



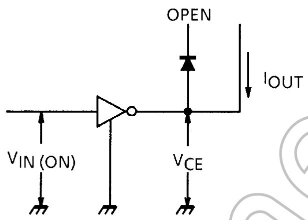
3. IIN (ON)



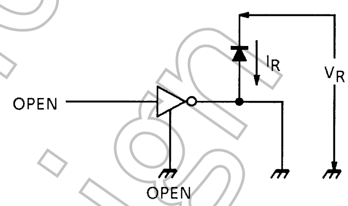
4. $I_{IN\ (OFF)}$



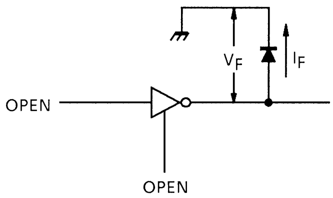
5. $V_{IN\ (ON)}$



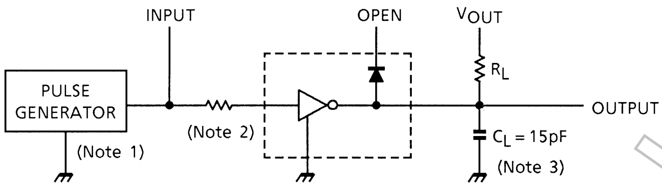
6. I_R

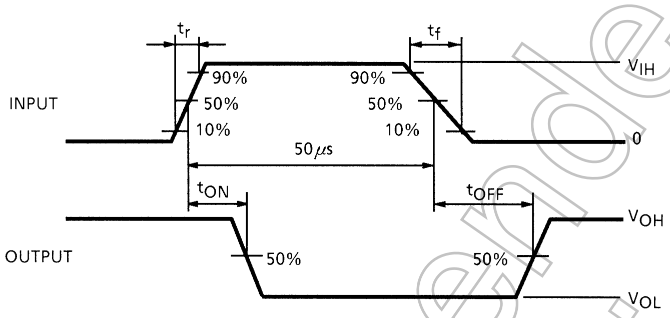


7. V_F



8. t_{ON}, t_{OFF}





Note 1: Pulse width 50 μs, duty cycle 10%
Output impedance 50 Ω, $t_r \leq 5$ ns, $t_f \leq 10$ ns

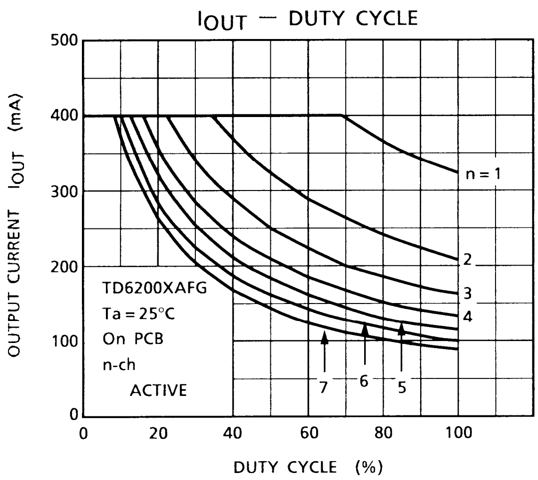
Note 2: Input condition

Type Number	V_{IH}
TD62003APG/AFG	3 V
TD62004APG/AFG	8 V

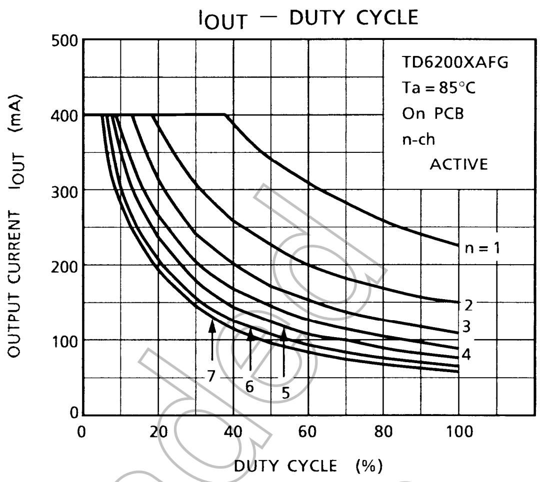
Note 3: C_L includes probe and jig capacitance.

Precautions for Using

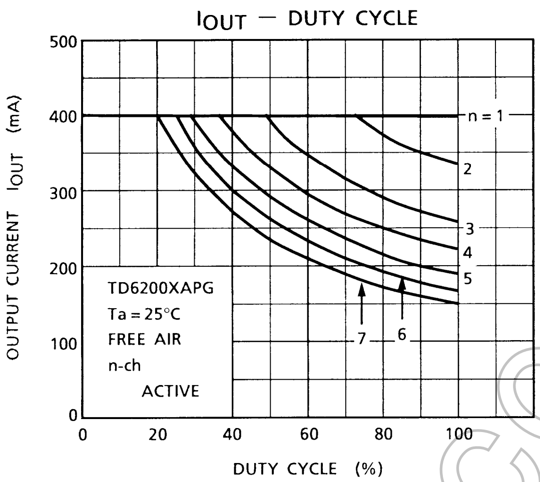
This IC does not include built-in protection circuits for excess current or overvoltage.
If this IC is subjected to excess current or overvoltage, it may be destroyed.
Hence, the utmost care must be taken when systems which incorporate this IC are designed.
Utmost care is necessary in the design of the output line, COMMON and GND line since IC may be destroyed due to short−circuit between outputs, air contamination fault, or fault by improper grounding.



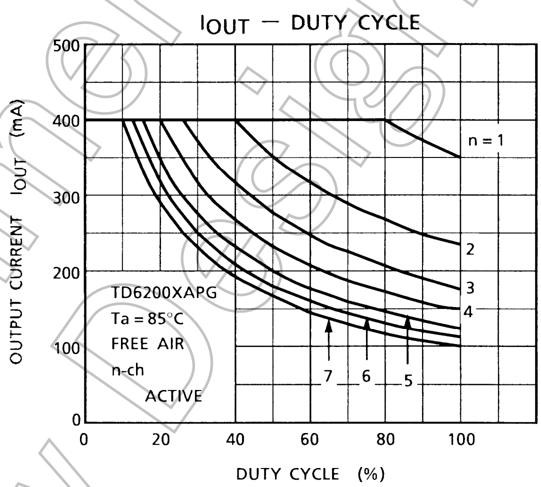
I_{OUT} – DUTY CYCLE
OUTPUT CURRENT I_{OUT} (mA)
DUTY CYCLE (%)
TD6200XAFG
Ta = 25°C
On PCB
n-ch
ACTIVE
n = 1
2
3
4
7
6
5



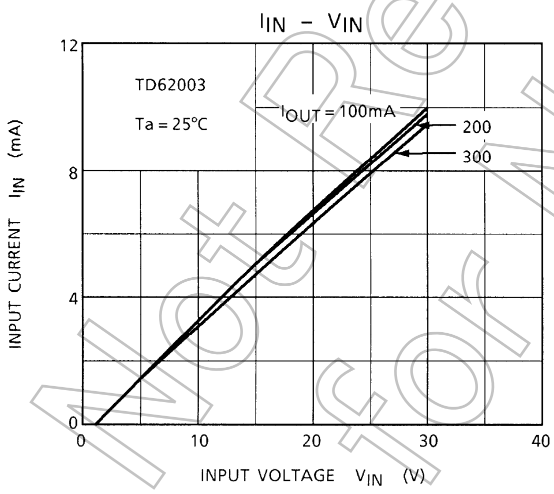
I_{OUT} – DUTY CYCLE
OUTPUT CURRENT I_{OUT} (mA)
DUTY CYCLE (%)
TD6200XAFG
Ta = 85°C
On PCB
n-ch
ACTIVE
n = 1
2
3
4
7
6
5



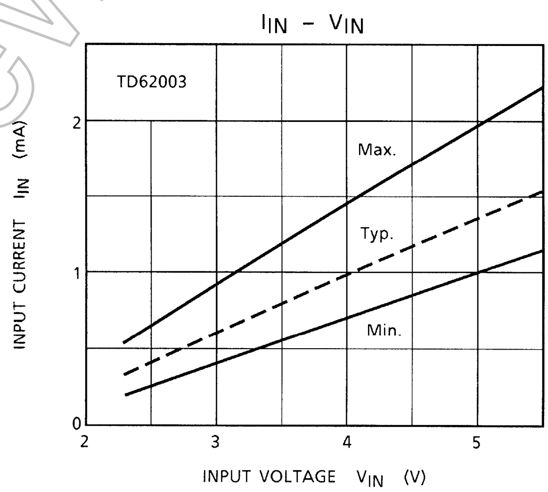
I_{OUT} – DUTY CYCLE
OUTPUT CURRENT I_{OUT} (mA)
DUTY CYCLE (%)
TD6200XAPG
Ta = 25°C
FREE AIR
n-ch
ACTIVE
n = 1
2
3
4
5
7
6



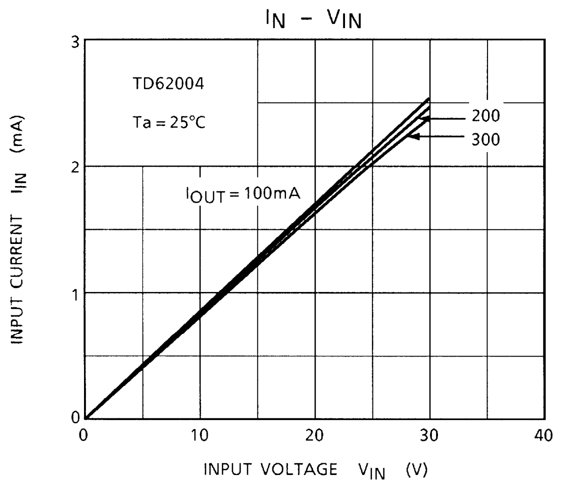
I_{OUT} – DUTY CYCLE
OUTPUT CURRENT I_{OUT} (mA)
DUTY CYCLE (%)
TD6200XAPG
Ta = 85°C
FREE AIR
n-ch
ACTIVE
n = 1
2
3
4
7
6
5

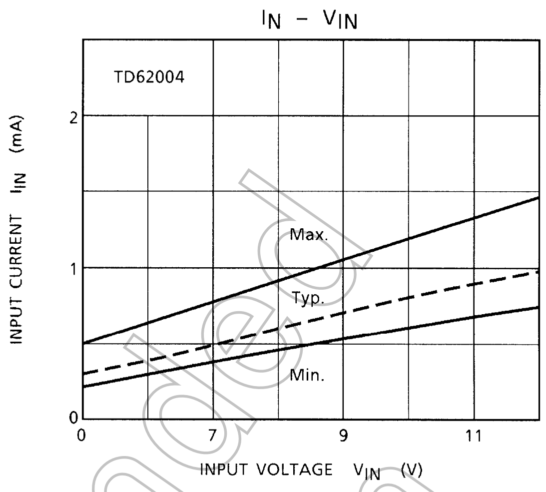


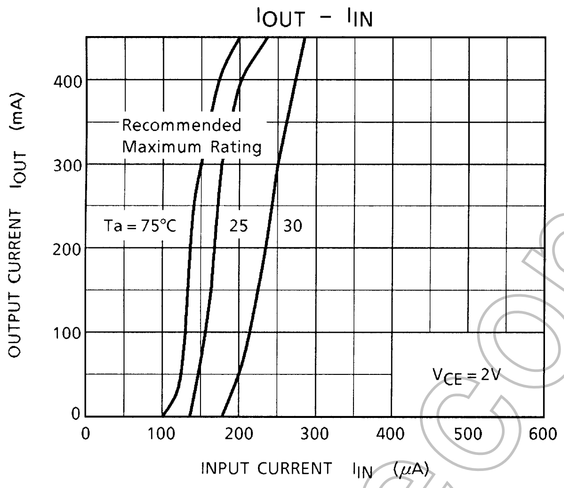
I_{IN} – V_{IN}
INPUT CURRENT I_{IN} (mA)
INPUT VOLTAGE V_{IN} (V)
TD62003
Ta = 25°C
I_{OUT} = 100mA
200
300

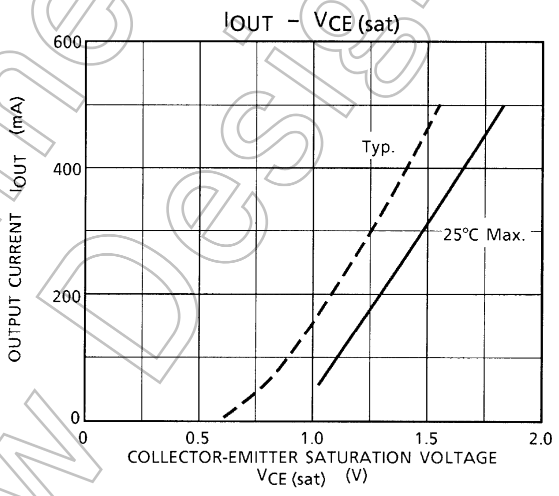


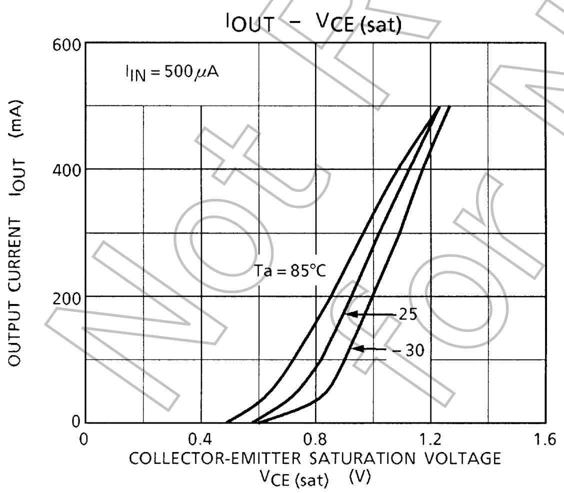
I_{IN} – V_{IN}
INPUT CURRENT I_{IN} (mA)
INPUT VOLTAGE V_{IN} (V)
TD62003
Max.
Typ.
Min.

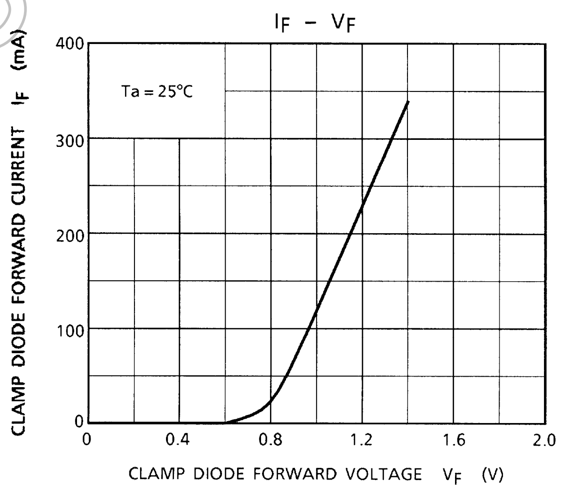

IN – VIN
TD62004
Ta = 25°C
IOUT = 100mA
200
300
INPUT CURRENT IIN (mA)
INPUT VOLTAGE VIN (V)

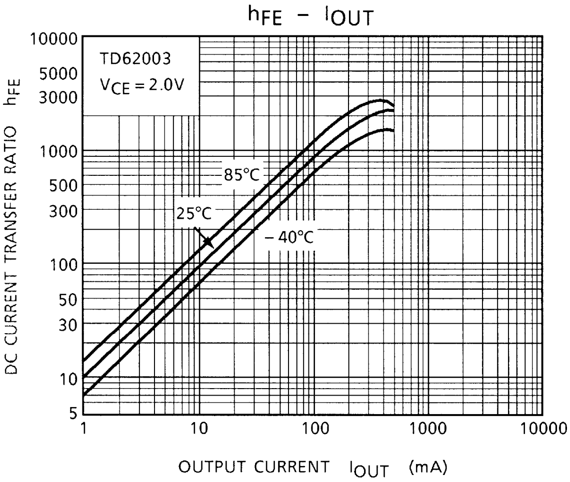

IN – VIN
TD62004
Max.
Typ.
Min.
INPUT CURRENT IIN (mA)
INPUT VOLTAGE VIN (V)

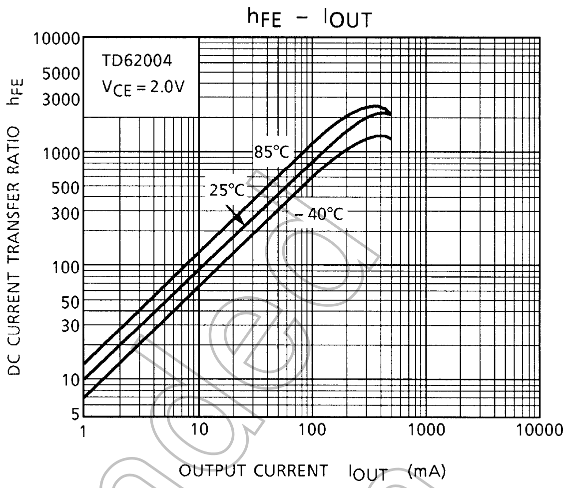

IOUT – IIN
Recommended
Maximum Rating
Ta = 75°C
25
30
VCE = 2V
OUTPUT CURRENT IOUT (mA)
INPUT CURRENT IIN (μA)

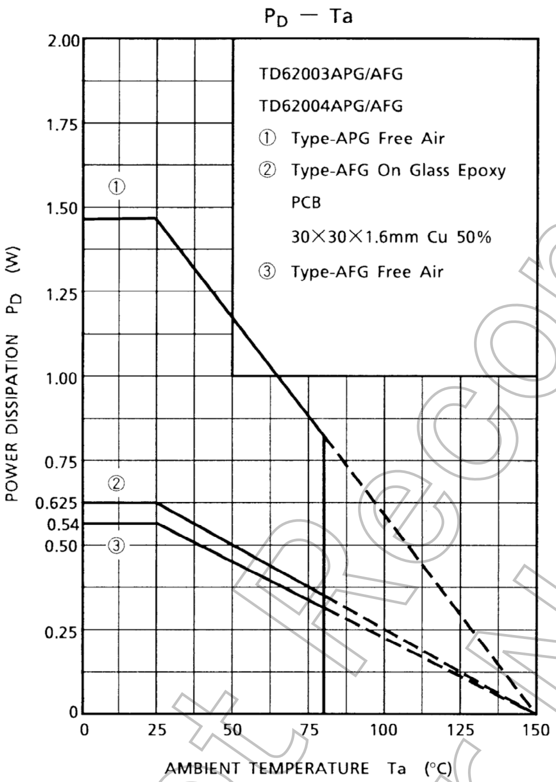

IOUT – VCE (sat)
Typ.
25°C Max.
OUTPUT CURRENT IOUT (mA)
COLLECTOR-EMITTER SATURATION VOLTAGE
VCE (sat) (V)


IOUT – VCE (sat)
IIN = 500μA
Ta = 85°C
25
– 30
OUTPUT CURRENT IOUT (mA)
COLLECTOR-EMITTER SATURATION VOLTAGE
VCE (sat) (V)


IF – VF
Ta = 25°C
CLAMP DIODE FORWARD CURRENT IF (mA)
CLAMP DIODE FORWARD VOLTAGE VF (V)

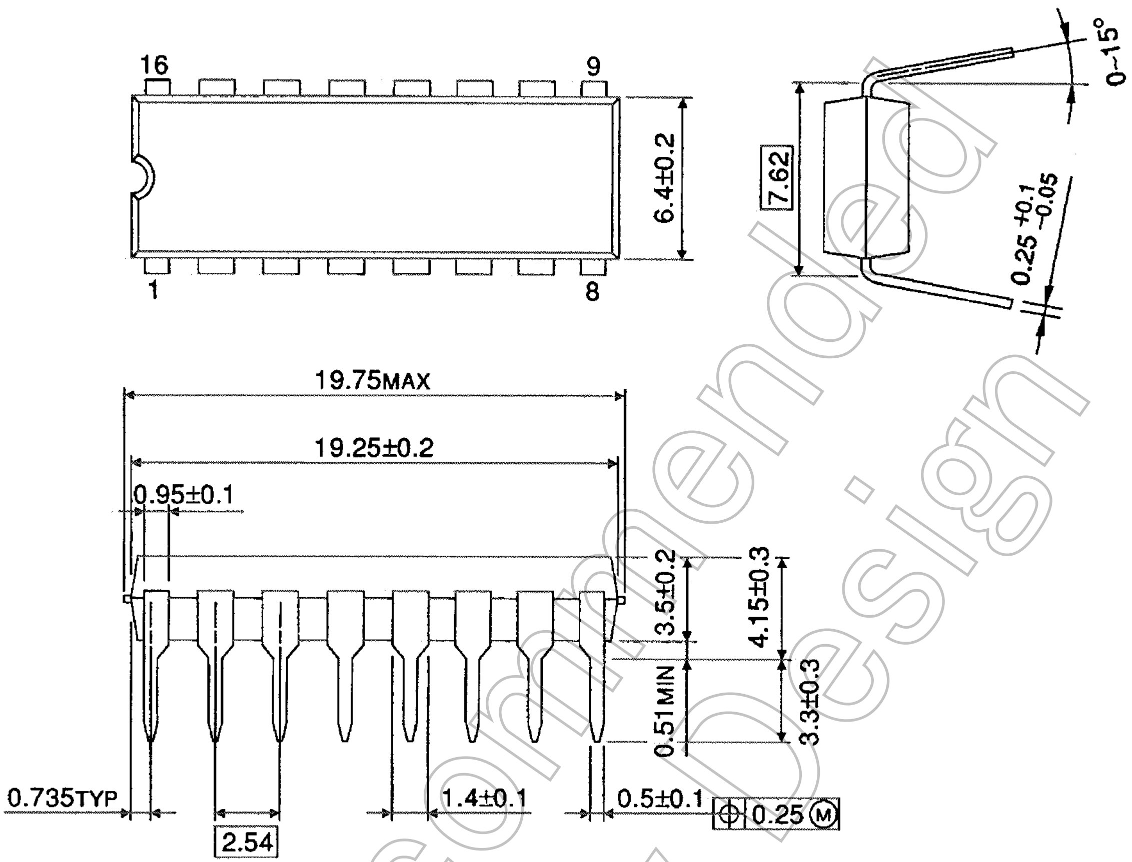

h_{FE} – I_{OUT}
TD62003
V_{CE} = 2.0V
85°C
25°C
−40°C
DC CURRENT TRANSFER RATIO h_{FE}
OUTPUT CURRENT I_{OUT} (mA)
10000
5000
3000
1000
500
300
100
50
30
10
5
1
10
100
1000
10000


h_{FE} – I_{OUT}
TD62004
V_{CE} = 2.0V
85°C
25°C
−40°C
DC CURRENT TRANSFER RATIO h_{FE}
OUTPUT CURRENT I_{OUT} (mA)
10000
5000
3000
1000
500
300
100
50
30
10
5
1
10
100
1000
10000


P_D — Ta
TD62003APG/AFG
TD62004APG/AFG
① Type-APG Free Air
② Type-AFG On Glass Epoxy PCB
30×30×1.6mm Cu 50%
③ Type-AFG Free Air
POWER DISSIPATION P_D (W)
AMBIENT TEMPERATURE Ta (°C)
2.00
1.75
1.50
1.25
1.00
0.75
0.625
0.54
0.50
0.25
0
0
25
50
75
100
125
150

Package Dimensions

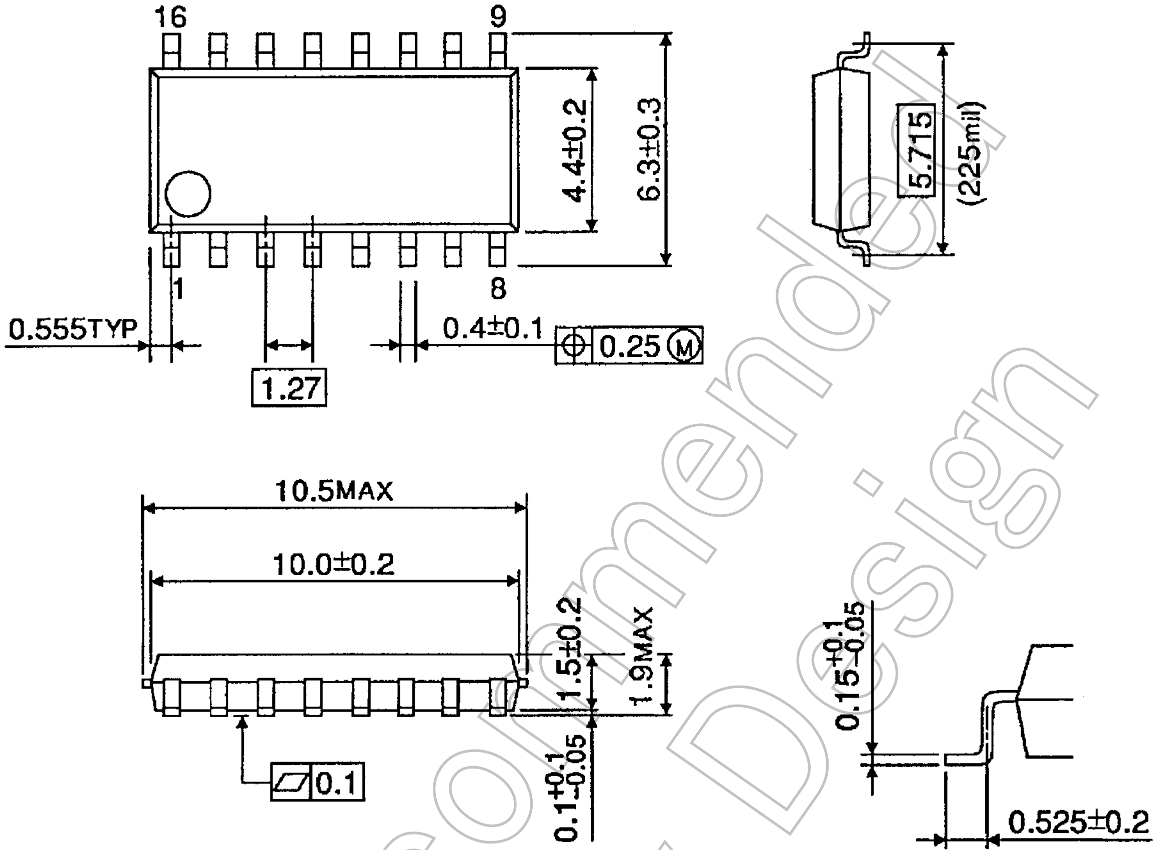
DIP16-P-300-2.54A Unit : mm



Weight: 1.11 g (Typ.)

Package Dimensions

SOP16-P-225-1.27 Unit : mm



Weight: 0.16 g (Typ.)

Notes on Contents

1. Equivalent Circuits

The equivalent circuit diagrams may be simplified or some parts of them may be omitted for explanatory purposes.

2. Test Circuits

Components in the test circuits are used only to obtain and confirm the device characteristics. These components and circuits are not guaranteed to prevent malfunction or failure from occurring in the application equipment.

IC Usage Considerations

Notes on Handling of ICs

(1) The absolute maximum ratings of a semiconductor device are a set of ratings that must not be exceeded, even for a moment. Do not exceed any of these ratings.
Exceeding the rating(s) may cause the device breakdown, damage or deterioration, and may result injury by explosion or combustion.

(2) Use an appropriate power supply fuse to ensure that a large current does not continuously flow in case of over current and/or IC failure. The IC will fully break down when used under conditions that exceed its absolute maximum ratings, when the wiring is routed improperly or when an abnormal pulse noise occurs from the wiring or load, causing a large current to continuously flow and the breakdown can lead smoke or ignition. To minimize the effects of the flow of a large current in case of breakdown, appropriate settings, such as fuse capacity, fusing time and insertion circuit location, are required.

(3) If your design includes an inductive load such as a motor coil, incorporate a protection circuit into the design to prevent device malfunction or breakdown caused by the current resulting from the inrush current at power ON or the negative current resulting from the back electromotive force at power OFF. IC breakdown may cause injury, smoke or ignition.
Use a stable power supply with ICs with built-in protection functions. If the power supply is unstable, the protection function may not operate, causing IC breakdown. IC breakdown may cause injury, smoke or ignition.

(4) Do not insert devices in the wrong orientation or incorrectly.
Make sure that the positive and negative terminals of power supplies are connected properly.
Otherwise, the current or power consumption may exceed the absolute maximum rating, and exceeding the rating(s) may cause the device breakdown, damage or deterioration, and may result injury by explosion or combustion.
In addition, do not use any device that is applied the current with inserting in the wrong orientation or incorrectly even just one time.

(5) Carefully select external components (such as inputs and negative feedback capacitors) and load components (such as speakers), for example, power amp and regulator.
If there is a large amount of leakage current such as input or negative feedback condenser, the IC output DC voltage will increase. If this output voltage is connected to a speaker with low input withstand voltage, overcurrent or IC failure can cause smoke or ignition. (The over current can cause smoke or ignition from the IC itself.) In particular, please pay attention when using a Bridge Tied Load (BTL) connection type IC that inputs output DC voltage to a speaker directly.

Points to Remember on Handling of ICs

(1) Heat Radiation Design

In using an IC with large current flow such as power amp, regulator or driver, please design the device so that heat is appropriately radiated, not to exceed the specified junction temperature (Tj) at any time and condition. These ICs generate heat even during normal use. An inadequate IC heat radiation design can lead to decrease in IC life, deterioration of IC characteristics or IC breakdown. In addition, please design the device taking into considerate the effect of IC heat radiation with peripheral components.

(2) Back-EMF

When a motor rotates in the reverse direction, stops or slows down abruptly, a current flow back to the motor's power supply due to the effect of back-EMF. If the current sink capability of the power supply is small, the device's motor power supply and output pins might be exposed to conditions beyond absolute maximum ratings. To avoid this problem, take the effect of back-EMF into consideration in system design.

About solderability, following conditions were confirmed

- Solderability

(1) Use of Sn-37Pb solder Bath
- solder bath temperature = 230°C
- dipping time = 5 seconds
- the number of times = once
- use of R-type flux

(2) Use of Sn-3.0Ag-0.5Cu solder Bath
- solder bath temperature = 245°C
- dipping time = 5 seconds
- the number of times = once
- use of R-type flux

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